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 Package Options Include Plastic Small-Outline (D) and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

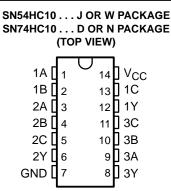
#### description

These devices contain three independent 3-input NAND gates. They perform the Boolean function  $Y = \overline{A \cdot B \cdot C}$  or  $Y = \overline{A} + \overline{B} + \overline{C}$  in positive logic.

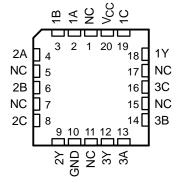
The SN54HC10 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74HC10 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

	FUNCTION TABLE (each gate)									
	INPUTS		OUTPUT							
Α	В	С	Y							
н	Н	Н	L							
L	Х	Х	н							
Х	L	Х	н							
Х	Х	L	н							

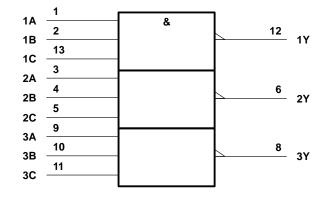
## logic symbol<sup>†</sup>



SN54HC10 . . . FK PACKAGE (TOP VIEW)

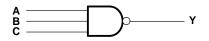


NC - No internal connection



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

## logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range<sup>†</sup>

Supply voltage range, $V_{CC}$
N package

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

#### recommended operating conditions

			S	SN54HC10			SN74HC10		
			MIN	MIN NOM MAX MIN NOM MAX		MAX	UNIT		
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			V
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			
		$V_{CC} = 6 V$	4.2			4.2			
	Low-level input voltage	V <sub>CC</sub> = 2 V	0		0.5	0		0.5	
VIL		$V_{CC} = 4.5 V$	0		1.35	0		1.35	V
		ACC = 6 A	0		1.8	0		1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
	Input transition (rise and fall) time	$V_{CC} = 2 V$	0		1000	0		1000	
tt		V <sub>CC</sub> = 4.5 V	0		500	0		500	ns
		VCC = 6 V	0		400	0		400	
TA	Operating free-air temperature		-55		125	-40		85	°C



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PARAMETER	TEST CONDITIONS		Vcc	T <sub>A</sub> = 25°C			SN54HC10		SN74HC10		LINUT	
PARAMETER				MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
VOH			2 V	1.9	1.998		1.9		1.9			
		I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4			
	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V	
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84			
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.8		5.2		5.34			
	VI = VIH or VIL	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	V	
			4.5 V		0.001	0.1		0.1		0.1		
VOL			6 V		0.001	0.1		0.1		0.1		
		IOL	I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26		0.4		0.33		
lj	$V_{I} = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA	
Icc	$V_{I} = V_{CC} \text{ or } 0,$	I <mark>O</mark> = 0	6 V			2		40		20	μΑ	
Ci			2 V to 6 V		3	10		10		10	pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

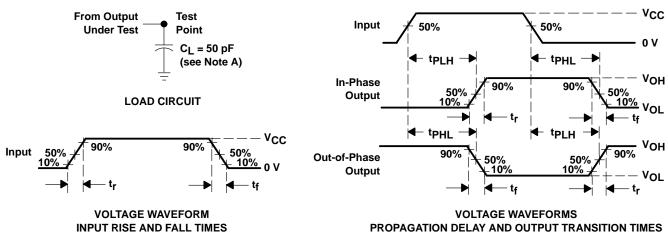
PARAMETER	FROM	то	$T_A =$		T <sub>A</sub> = 25°C		SN54HC10		SN74HC10		UNIT				
	(INPUT)	(INPUT)	(OUTPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
	A, B, or C	Y		2 V		35	95		145		120				
<sup>t</sup> pd			4.5 V		10	19		29		24	ns				
										6 V		9	16		25
tt				2 V		23	75		110		95				
		Y	4.5 V		6	15		22		19	ns				
			6 V		5	13		19		16					

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cp	Power dissipation capacitance per gate	No load	25	pF



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### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 1. Load Circuit and Voltage Waveforms



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